₩<u>895</u> <u>Semiconductor</u> DS92LX1621 / DS92LX1622

10 - 50 MHz DC-Balanced Channel Link III Serializer and Deserializer with Bi-Directional Control Channel

General Description

The DS92LX1621 / DS92LX1622 chipset offers a Channel Link III interface with a high-speed forward channel and a fullduplex back channel for data transmission over a single differential pair. The Serializer/Deserializer pair is targeted for direct connections between automotive camera systems and Host Controller/Electronic Control Unit (ECU). The primary transport sends 16 bits of image data over a single high-speed serial stream together with a low latency bi-directional control channel transport that supports I²C. Included with the 16-bit payload is a selectable data integrity option for CRC (Cyclic Redundancy Check) or parity bit to monitor transmission link errors. Using National's embedded clock technology allows transparent full-duplex communication over a single differential pair, carrying asymmetrical bi-directional control information without the dependency of video blanking intervals. This single serial stream simplifies transferring a wide data bus over PCB traces and cable by eliminating the skew problems between parallel data and clock paths. This significantly saves system cost by narrowing data paths that in turn reduce PCB layers, cable width, and connector size and pins.

In addition, the Deserializer inputs provide equalization control to compensate for loss from the media over longer distances. Internal DC balanced encoding/decoding is used to support AC-Coupled interconnects.

The sleep function provides a power-savings mode and a remote wake up interrupt for signaling of a remote device. The Serializer is offered in a 32-pin LLP package, and Deserializer is offered in a 40-pin LLP package.

Features

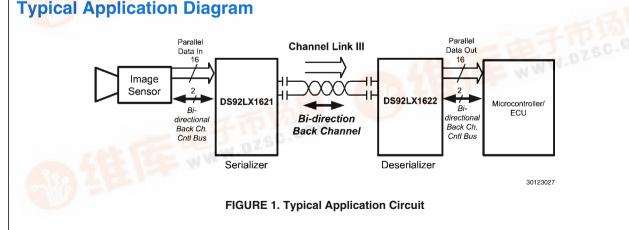
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- Configurable data throughput
 - 12-bit (min) up to 600 Mbits/sec
 - 16-bit (def) up to 800 Mbits/sec
 - 18-bit (max) up to 900 Mbits/sec
- 10 MHz to 50 MHz input clock support

- Embedded clock with DC Balanced coding to support ACcoupled interconnects
- Capable to drive up to 10 meters shielded twisted-pair
- Bi-directional control interface channel with I²C support
- I²C interface for device configuration. Single-pin ID addressing
- 16-bit data payload with CRC (Cyclic Redundancy Check) for checking data integrity with programmable data transmission error detection and interrupt control
- Up to 6 Programmable GPIO's
- AT-SPEED BIST diagnosis feature to validate link integrity
- Individual power-down controls for both SER and DES
- User-selectable clock edge for parallel data on both SER and DES
- Integrated termination resistors
- 1.8V- or 3.3V-compatible parallel bus interface
- Single power supply at 1.8V
- IEC 61000–4–2 ESD compliant
- No reference clock required on Deserializer
- Programmable Receive Equalization
- LOCK output reporting pin to ensure link status
- EMI/EMC Mitigation
- DES Programmable Spread Spectrum (SSCG) outputs
- DES Receiver staggered outputs
- Temperature range –40°C to +85°C
- SER package: 32 pin LLP (5mm x 5mm)
- DES package: 40 pin LLP (6mm x 6mm)

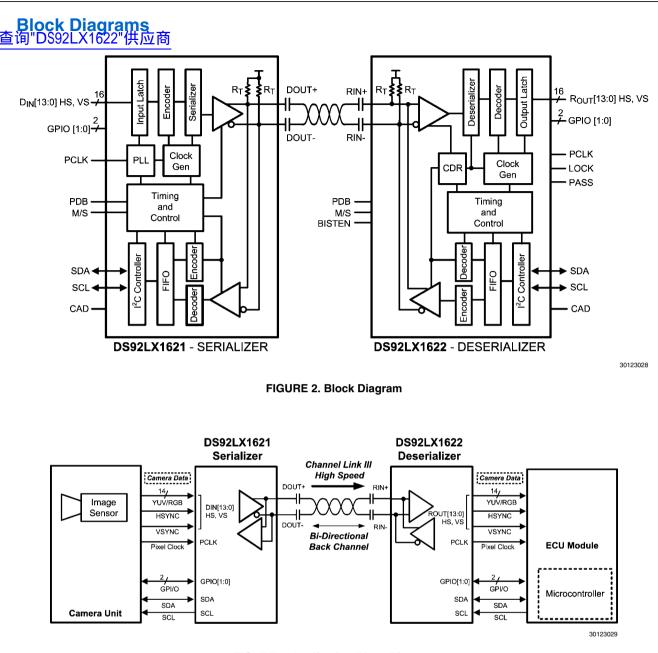
Applications

- Industrial Displays, Touch Screens
- Medical Imaging



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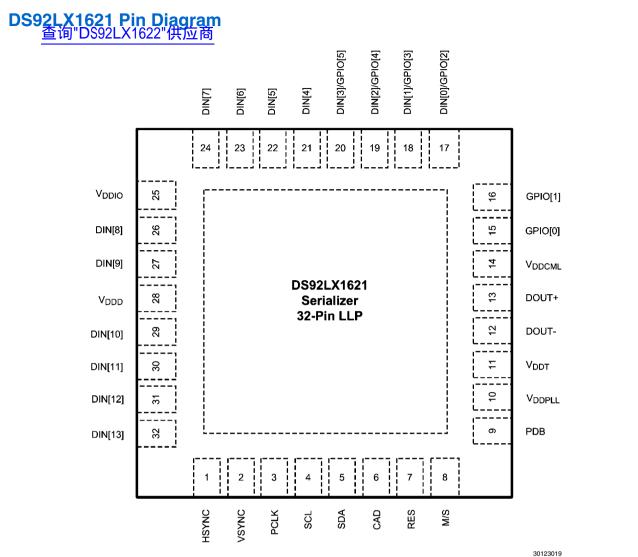
Ordering Information

NSID	Package Description	Quantity	SPEC	Package ID
DS92LX1621SQE	32-pin LLP, 5.0 X 5.0 X 0.8 mm, 0.5 mm pitch	250	NOPB	SQA32A
DS92LX1621SQ	32-pin LLP, 5.0 X 5.0 X 0.8 mm, 0.5 mm pitch	1000	NOPB	SQA32A
DS92LX1621SQX	32-pin LLP, 5.0 X 5.0 X 0.8 mm, 0.5 mm pitch	4500	NOPB	SQA32A
DS92LX1622SQE	40-pin LLP, 6.0 X 6.0 X 0.8 mm, 0.5 mm pitch	250	NOPB	SQA40A
DS92LX1622SQ	40-pin LLP, 6.0 X 6.0 X 0.8 mm, 0.5 mm pitch	1000	NOPB	SQA40A
DS92LX1622SQX	40-pin LLP, 6.0 X 6.0 X 0.8 mm, 0.5 mm pitch	4500	NOPB	SQA40A

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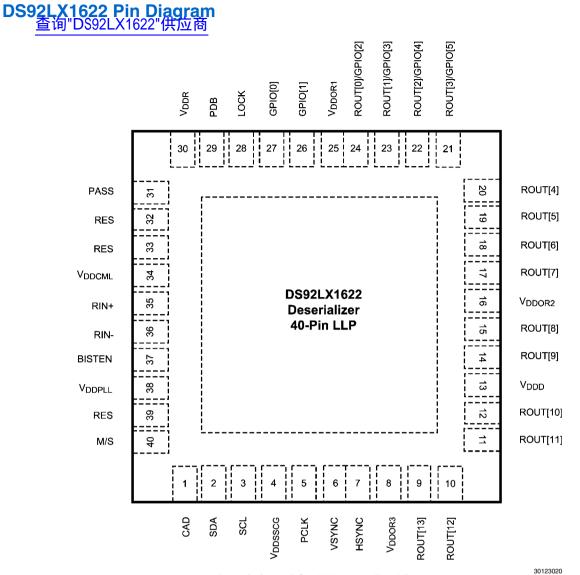
DS92LX1621 / DS92LX1622

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Pin Name	Pin No.	I/O, Type	Description
	ALLEL INTERFAC		
DIN[13:0]	32, 31, 30, 29, 27, 26, 24, 23, 22, 21, 20, 19,	Inputs, LVCMOS w/ pull down	Parallel data inputs.
HSYNC	18, 17 1	Inputs, LVCMOS w/ pull down	Parallel data input 14, typically used as Horizontal SYNC Input
VSYNC	2	Inputs, LVCMOS w/ pull down	Parallel data input 15, typically used as Vertical SYNC Input
PCLK	3	Input, LVCMOS w/ pull down	Pixel Clock Input Pin. Strobe edge set by TRFB control register.
GENERAL PUP	RPOSE INPUT OU	TPUT (GPIO)	
DIN[3:0]/	20, 19, 18, 17	Input/Output, Digital	DIN[3:0] general-purpose pins can be individually configured as either inputs
GPIO[5:2]	ļ		or outputs; used to control and respond to various commands.
GPIO[1:0]	16, 15	Input/Output, Digital	General-purpose pins can be individually configured as either inputs or outputs; used to control and respond to various commands.
SERIAL CONT	ROL BUS - I ² C CC	MPATIBLE	r
SCL	4	Input/Output, Digital	Clock line for the serial control bus communication SCL requires an external pull-up resistor to V _{DDIO} .
SDA	5	Input/Output, Open Drain	Data line for the serial control bus communication SDA requires an external pull-up resistor to V _{DDIO} .
M/S	8	Input, LVCMOS w/ pull down	I ² C Mode Select M/S = L, Master (default); device generates and drives the SCL clock line M/S = H, Slave; device accepts SCL clock input
CAD	6	Input, analog	Continuous Address Decoder Input pin to select the Slave Device Address. Input is connect to external resistor divider to programmable Device ID address (see Serial Control Bus Connection).
CONTROL ANI	CONFIGURATIO	N	
PDB	9	Input, LVCMOS w/ pull down	Power down Mode Input Pin. PDB = H, Transmitter is enabled and is ON. PDB = L, Transmitter is in Sleep (Power Down). When the transmitter is in the SLEEP state, the PLL is shutdown, and IDD is minimized.
RES	7	Input, LVCMOS w/ pull down	Reserved. This pin MUST be tied LOW.
Channel Link I	II INTERFACE		
DOUT+	13	Input/Output, CML	Non-inverting differential output, back-channel input.
DOUT-	12	Input/Output, CML	Inverting differential output, back-channel input.
Power and Gro	ound		
VDDPLL	10	Power, Analog	PLL Power, 1.8V ±5%
VDDT	11	Power, Analog	Tx Analog Power, 1.8V ±5%
VDDCML	14	Power, Analog	LVDS & BC Dr Power, 1.8V ±5%
VDDD	28	Power, Digital	Digital Power, 1.8V ±5%
VDDIO	25	Power, Digital	Power for input stage, The single-ended inputs are powered from V _{DDIO} .
VSS	DAP	Ground, DAP	DAP must be grounded. Connect to ground plane with at least 9 vias.





Pin Name	Pin No.	ializer Pin De	Description
LVCMOS PAR	ALLEL INTERFAC		
ROUT[13:0]	9, 10, 11, 12, 14, 15, 17, 18, 19, 20, 21, 22, 23, 24	Outputs, LVCMOS	Parallel data outputs.
HSYNC	7	Output, LVCMOS	Parallel data output 14, typically used as Horizontal SYNC output
VSYNC	6	Output, LVCMOS	Parallel data output 14, typically used as Vertical SYNC output
PCLK	5	Output, LVCMOS	Pixel Clock Output Pin. Strobe edge set by RRFB control register
General Purpos	se Input Output (GI	PIO)	•
ROUT[3:0] / GPIO[5:2]	21, 22, 23, 24	Input/Output, Digital	ROUT[3:0] general-purpose pins can be individually configured as either inputs or outputs; used to control and respond to various commands.
GPIO[1:0]	26, 27	Input/Output, Digital	General-purpose pins can be individually configured as either inputs or outputs; used to control and respond to various commands.
SERIAL CONT	ROL BUS - I ² C CC	MPATIBLE	
SCL	3	Input/Output, Digital	Clock line for the serial control bus communication SCL requires an external pull-up resistor to V_{DDIO} .
SDA	2	Input/Output, Open Drain	Data line for serial control bus communication SDA requires an external pull-up resistor to V _{DDIO} .
M/S	40	Input, LVCMOS w/ pull up	I ² C Mode Select M/S = L, Master; device generates and drives the SCL clock line M/S = H, Slave (default); device accepts SCL clock input
CAD	1	Input, analog	Continuous Address Decoder Input pin to select the Slave Device Address. Input is connect to external resistor divider to programmable Device ID address (see Serial Control Bus Connection)
CONTROL AN	D CONFIGURATIO	DN	
PDB	29	Input, LVCMOS w/ pull down	Power down Mode Input Pin. PDB = H, Receiver is enabled and is ON. PDB = L, Receiver is in Sleep (Power down mode). When the Receiver is i the SLEEP state, the LVCMOS Outputs are in TRI-STATE, the PLL is shutdown and IDD is minimized.
LOCK	28	Output, LVCMOS	LOCK Status Output Pin. LOCK = H, PLL is Locked, outputs are active LOCK = L, PLL is unlocked, ROUT and PCLK output states are controlled b OSS_SEL. May be used as Link Status.
PASS	31	Output, LVCMOS	When BISTEN = L; Normal operation PASS is high to indicate no errors are detected. The PASS pin asserts low to indicate a CRC error was detected on the link.
RES	32, 33, 39	-	Reserved. Pin 39: This pin MUST be tied LOW. Pins 32, 33: Leave pin open.
BIST MODE	-1		
BISTEN	37	Input, LVCMOS w/ pull down	BIST Enable Pin. BISTEN = H, BIST Mode is enabled. BISTEN = L, BIST Mode is disabled.
PASS	31	Output, LVCOMS	PASS Output Pin for BIST mode. PASS = H, ERROR FREE Transmission PASS = L, one or more errors were detected in the received payload.

	Din No.		Description	
Pin Name	Pin No.	I/O, Type	Description	
RIN+ <u></u> 查询	DS92L3X1622"	Hoputo utput, CML	Noninverting differential input, back channel output.	
RIN-	36	Input/Output, CML	Inverting differential input, back channel output.	
POWER AND G	ROUND	-		
VDDSSCG 4 Digital Power SSCG Power, 1.8V ±5%				
VDDSSCG I 4 I Digital Power I		Power supply must be connect regardless if SSCG function is in operation		
VDDOR1/2/3	TTL Output Buffer Power, The single-ended outputs and control inp		TTL Output Buffer Power, The single-ended outputs and control input are	
VDDOR1/2/3	25, 16, 8	Digital Power	powered from V_DDIO. V_DDIO can be connected to a 1.8V ±5% or 3.3V ±10%	
VDDD	13	Digital Power	Digital Core Power, 1.8V ±5%	
VDDR	30	Analog Power	Rx Analog Power, 1.8V ±5%	
VDDCML	34	Analog Power	Bi-Directional Control Channel Driver Power, 1.8V ±5%	
VDDPLL	38	Analog Power	PLL Power, 1.8V ±5%	
VSS	DAP	Ground	DAP must be grounded. Connect to the ground plane with at least 16 vias.	

Absolute Maximum Ratings (Note 1) IT Miniary Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage (V _{DD1V8})	-0.3V to +2.5V
Supply Voltage (V _{DD3V3})	-0.3V to +4.0V
LVCMOS Input Voltage (V _{DD1V8})	-0.3V to +(V _{DD1V8} + 0.3V)
LVCMOS Input Voltage (V _{DD3V3})	-0.3V to +(V _{DD3V3} + 0.3V)
LVCMOS Output Voltage (V _{DD})	-0.3V to +(V _{DD} + 0.3V)
CML Driver I/O Voltage (V _{DD1V8})	-0.3V to (V _{DD1V8} + 0.3V)
CML Receiver I/O Voltage	
(V _{DD1V8})	-0.3V to (V _{DD1V8} + 0.3V)
Junction Temperature	+150°C
Storage Temperature	–65°C to +150°C
Maximum Package Power Dissipation Capacity	1/θJA °C/W above +25°
Package Derating: DS92LX1621 32L LLP	
θ _{JA} (based on 9 thermal vias)	34.3 °C/W
θ_{JC} (based on 9 thermal vias)	6.9 °C/W
Maximum Package Power Dissipation Capacity Package	1/θ _{JA} °C/W above +25°
Package Derating: DS92LX1622 40L LLP	
θ _{JA} (based on 16 thermal vias)	28.0 °C/W

θ _{JC} (based on 16 thermal vias)	4.4 °C/W
ESD Rating (IEC 61000-4-2)	$RD = 330\Omega, CS = 150pF$
Air Discharge (DOUT+, DOUT-, RIN+, RIN-) Contact Discharge (DOUT+, DOUT-, RIN+,	≥±25 kV
RIN-)	≥±10 kV
ESD Rating (HBM)	≥±8 kV

Recommended Operating Conditions

	Min	Nom	Max	Units	
V _{DD} (1.8V)	1.71	1.8	1.89	V	
V _{DDIO} (1.8V Mode)	1.71	1.8	1.89	V	
V _{DDIO} (3.3V Mode)	3	3.3	3.6	V	
Supply Noise					
V _{DDn} (1.8V)			25	mVp-p	
V _{DDIO} (1.8V)			25	mVp-p	
V _{DD3V3}			50	mVp-p	
Operating Free Air Temperature (T _A)	-40	25	85	°C	
Input Clock Rate	10		50	MHz	

θ_{IA} (based on 16 thermal vias)

Serializer Electrical Characteristics (Note 2, Note 3, Note 4)

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditio	ns	Min	Тур	Max	Units
LVCMOS	DC SPECIFICATIONS 3.3V I/C	(SER INPUTS, DES OUT	PUTS, GPIO, CON	TROL INPU	TS AND C	UTPUTS)	
V _{IH}	High Level Input Voltage	VIN = 3.0V to 3.6V		2.0		V _{IN}	V
V _{IL}	Low Level Input Voltage	VIN = 3.0V to 3.6V		GND		0.8	V
I _{IN}	Input Current	VIN = 0V or 3.6V VIN = 3.0V to 3.6V		-20	±1	+20	μA
V _{OH}	High Level Output Voltage	V _{DDIO} = 3.0V to 3.6V		2.4		V _{DDIO}	V
V _{OL}	Low Level Output Voltage	$V_{DDIO} = 3.0V$ to 3.6V $I_{OH} = +4mA$		GND		0.4	V
I _{os}	Output Short Circuit Current	V _{OUT} = 0V	Serializer GPIO Outputs		-24		
			Deserializer LVCMOS Outputs		-39		mA
l _{oz}	TRI-STATE® Output Current	PDB = 0V, V _{OUT} = 0V or V _{DD}	LVCMOS Outputs	-20	±1	+20	μA
LVCMOS	DC SPECIFICATIONS 1.8V I/C	(TX INPUTS, RX OUTPU	TS, GPIO, CONTR	OL INPUTS	AND OUT	PUTS)	
V _{IH}	High Level Input Voltage	V _{IN} = 1.71V to 1.89V		0.65 V _{IN}		V _{IN} +0.3	v
V _{IL}	Low Level Input Voltage	V _{IN} = 1.71V to 1.89V		GND		0.35 V _{IN}	v
I _{IN}	Input Current	V _{IN} = 0V or 1.89V V _{IN} = 1.71V to 1.89V		-20	±1	+20	μA
V _{OH}	High Level Output Voltage	V _{DDIO} = 1.71V to 1.89V I _{OH} = -4mA		V _{DDIO} - 0.45		V _{DDIO}	V
V _{OL}	Low Level Output Voltage	V _{DDIO} = 1.71V to 1.89V I _{OL} = +4 mA		GND		0.45	V

Symbol	Parameter	Conditions	6	Min	Тур	Мах	Units
I _{os}	OELP LA SASIL XILGAZ CUTTERY P	V _{OUT} = 0V (<i>Note 10</i>)	Serializer GPIO Outputs		-11		
			Deserializer LVCMOS Outputs		-20		mA
I _{oz}	TRI-STATE® Output Current	PDB = 0V, VOUT = 0V or VDD	LVCMOS Outputs	-20	±1	+20	μA
CML DRIV	ER DC SPECIFICATIONS (DC)UT+, DOUT-)					
IV _{OD} I	Output Differential Voltage	R _T = 100Ω		268	340	412	mV
ΔV _{OD}	Output Differential Voltage Unbalance	R _L = 100Ω			1	50	mV
V _{os}	Output Differential Offset Voltage	R _L = 100Ω (<i>Figure 7</i>)		V _{DD (MIN)} - V _{OD (MAX)}	V _{DD} - V _{OD}	V _{DD (MAX)} - V _{OD (MIN)}	V
ΔV _{os}	Offset Voltage Unbalance	R _L = 100Ω			1	50	mV
I _{OS}	Output Short Circuit Current	DOUT+/- = 0V, PDB = L or H (<i>Note 10</i>)			-27		mA
R _T	Differential Internal Termination Resistance	Differential across DOUT+	and DOUT-	80	100	120	Ω
CML REC	EIVER DC SPECIFICATIONS (RIN+, RIN-)			<u> </u>		
V _{TH}	Differential Threshold High Voltage					+90	
V _{TL}	Differential Threshold Low Voltage	Figure 8		-90			- mV
V _{IN}	Differential Input Voltage Range	RIN+ - RIN-		180			mV
I _{IN}	Input Current	$V_{IN} = V_{DD} \text{ or } 0V,$ $V_{DD} = 1.89V$		-20		+20	μA
R _T	Differential Internal Termination Resistance	Differential across RIN+ an	d RIN-	80	100	120	Ω
SER/DES	SUPPLY CURRENT *DIGITAL	, PLL, AND ANALOG VDD	S				
I _{DDT}	Serializer (Tx) Total Supply Current Mode	RT = 100Ω WORST CASE pattern (<i>Figure 5</i>)	VDDn = 1.89V, f = 50MHz		62	90	mA
	(includes load current)	$RT = 100\Omega$ RANDOM PRBS-7 pattern	Default Registers		55		
I _{DDIOT}	Serializer (Tx) VDDIO Supply Current (includes load current)	$RT = 100\Omega$ WORST CASE pattern ()	VDDn = 1.89V, f = 50MHz Default Registers		2	5	
			VDDn = 3.6V, f = 50MHz Default Registers		7	15	mA
1			V _{DD} = 1.89V		370	775	
IDDTZ	Serializer (Tx) Supply Current Power-down	PDB = 0V; All other LVCMOS Inputs = 0V	V _{DDIO} = 1.89V		55	125	μA
I _{DDIOTZ}			V _{DDIO} = 3.6V		65	135	

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Symbol	Parameter	Condition	าร	Min	Тур	Max	Units
查询"DSS	2LX1622"供应商 Deserializer (Rx) Supply Current (includes load	V _{DDn} = 1.89V CL = 8pF WORST CASE Pattern (<i>Figure 5</i>)	f = 50 MHz SSCG[3:0] = ON Default Registers		60	96	
	current)	V _{DDn} = 3.6V CL = 8pF WORST CASE Pattern	f = 50 MHz Default Registers		53		mA
I _{DDIOR}	Deserializer (Rx) VDDIO Supply Current (includes load current)	$V_{DDIO} = 1.89V$ CL = 8pF WORST CASE Pattern (<i>Figure 5</i>)	f = 50 MHz Default Registers		16	25	
		V _{DDIO} = 3.6V CL = 8pF Worst Case Pattern	f = 50 MHz Default Registers		38	64	
I _{DDRZ}	Deserializer (Rx) Supply Current Power-down	PDB = 0V; All other LVCMOS Inputs = 0V	V _{DDn} = 1.89V V _{DDIO} = 1.89V		42 8	400 40	μA
IDDIORZ			$V_{DDIO} = 3.6V$		350	800	

Recommended Serializer Timing for PCLK

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{TCP}	Transmit Clock Period	10 MHz — 50 MHz	20	Т	100	ns
t _{TCIH}	Transmit Clock Input High Time		0.4T	0.5T	0.6T	ns
t _{TCIL}	Transmit Clock Input Low Time		0.4T	0.5T	0.6T	ns
t _{CLKT}	PCLK Input Transition Time		0.5		2.4	ns
f _{osc}	Internal oscillator clock source			25		MHz

Serializer Switching Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{LHT}	CML Low-to-High Transition Time	RL = 100Ω (<i>Figure 6</i>)		150	330	ps
t _{HLT}	CML High-to-Low Transition Time	-		150	330	ps
t _{DIS}	Data Input Setup to PCLK	Carializar Data Insuta (Figure 10)	2.0			ns
t _{DIH}	Data Input Hold from PCLK	Serializer Data Inputs (<i>Figure 10</i>)	2.0			ns
t _{PLD}	Serializer PLL Lock Time	RL = 100Ω ((<i>Note 5</i> , <i>Note 9</i>))		1	2	ms
t _{SD}	Serializer Delay	$R_{T} = 100\Omega$ f = 10-50 MHz Reg Address 0x03h b[0] (TRFB = 1) (<i>Figure 12</i>)	6.386T + 5	6.386T + 12	6.386T + 19.7	ns
t _{JIND}	Serializer Output Deterministic Jitter	Serializer output intrinsic deterministic jitter. Measure with PRBS-7 test pattern. PCLK = 50 MHz		0.13		UI

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{JINR} 查询	Benanzer O Giput manadorini Jitter	Serializer output intrinsic random jitter (cycle-cycle). Alternating – 1,0 pattern.		0.04		UI
t _{JINT}	Peak-to-peak Serializer Output Jitter	Serializer output peak-to-peak jitter includes deterministic jitter, random jitter, and jitter transfer from serializer input. Measure with PRBS-7 test pattern.		0.396		UI
λ _{STXBW} Serializer Jitter Transfer Function -3 dB Bandwidth		PCLK = 50 MHz Default Registers		1.9		MHz
δ _{STX} Serializer Jitter Transfer Function		PCLK = 50 MHz Default Registers		0.944		dB
		PCLK = 50 MHz Default Registers		500		kHz

Description: Description Switching Characteristics Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Pin/Freq.	Min	Тур	Max	Units
t _{RCP}	Receiver Output Clock Period	$t_{RCP} = t_{TCP}$	PCLK	20	Т	100	ns
t _{PDC}	PCLK Duty Cycle	Default Registers SSCG[3:0] = OFF	PCLK	45	50	55	%
t _{CLH}	LVCMOS Low-to-High Transition Time	V_{DDIO} : 1.71V to 1.89V or 3.0V to 3.6V, C _L = 8 pF	PCLK	1.3	2.0	2.8	
CHL	LVCMOS High-to-Low Transition Time	(lumped load) Default Registers ((<i>Note 10</i>))		1.3	2.0	2.8	ns
CLH	LVCMOS Low-to-High Transition Time	V_{DDIO} : 1.71V to 1.89V or 3.0V to 3.6V, $C_{L} = 8 \text{ pF}$	Deserializer Data	1.6	2.4	3.3	
^I CHL	LVCMOS High-to-Low Transition Time	(lumped load) Default Registers () (<i>Note 9</i>)	Outputs	1.6	2.4	3.3	ns
ROS	ROUT Setup Data to PCLK	V _{DDIO} : 1.71V to 1.89V or		0.38T	0.5T		
t _{ROH}	ROUT Hold Data to PCLK	3.0V to 3.6V, CL = 8pF (lumped load) Default Registers ()	Deserializer Data Outputs	0.38T	0.5T		ns
DD	Deserializer Delay	Default Registers Register 0x03h b[0] (RRFB = 1)	10 MHz-50 MHz	4.571T + 8	4.571T + 12	4.571T + 16	ns
DDLT	Deserializer Data Lock Time		10 MHz-50 MHz			10	ms
RJIT	Receiver Input Jitter Tolerance		50 MHz		0.53		UI
	Receiver Clock Jitter	PCLK	10 MHz		300	550	
RDJ	Receiver Clock Siller	SSCG[3:0] = OFF	50 MHz		120	250	ps
	Deserializer Period Jitter	PCLK	10 MHz		425	600	ps
DPJ	Desenalizer r enoù siller	SSCG[3:0] = OFF	50 MHz		320	480	- p3
рссл	Deserializer Cycle-to-Cycle Clock	PCLK	10 MHz		320	500	ps
DCCJ	Jitter	SSCG[3:0] = OFF	50 MHz		300	500	
dev	Spread Spectrum Clocking Deviation Frequency	LVCMOS Output Bus	20 MHz-50 MHz		±0.5% to ±2.0%		%
fmod	Spread Spectrum Clocking Modulation Frequency	(Figure 17)	20 MHz-50 MHz		±9 kHz to ±66 kHz		kHz

Symbol	Parameter	Conditions	Min	Тур	Max	Units
RECOMM	ENDED INPUT TIMING REQUIREMEN	TSRECOMMENDED INPUT TIMING	REQUIREM	IENTS ((<mark>No</mark> i	te 13))	
f _{SCL}	SCL Clock Frequency		>0		100	kHz
f _{LOW}	SCL Low Period	f _{SCL} = 100 kHz	4.7			μs
f _{HIGH}	SCL High Period		4.0			μs
t _{HD:STA}	Hold time for a start or a repeated start condition		4.0			μs
t _{SU:STA}	Set Up time for a start or a repeated start condition		4.7			μs
t _{HD:DAT}	Data Hold Time		0		3.45	μs
t _{SU:DAT}	Data Set Up Time		250			ns
t _{SU:STO}	Set Up Time for STOP Condition,		4.0			μs
t _r	SCL & SDA Rise Time				1000	ns
t _f	SCL & SDA Fall Time				300	ns
C _b	Capacitive load for bus				400	pF
SWITCHI	NG CHARACTERISTICS ((<i>Note 9</i>))					
f	SCL Clock Frequency	Serializer M/S = 0 – R/W Register 0x05 = 0x40'h		100		kHz
f _{SCL}		Deserializer M/S = 0 - READ Register 0x06 b[6:4] = 0x00'h		100		KLIZ
f _{LOW}	SCL Low Period	Serializer M/S = $0 - R/W$ Register 0x05 = 0x40'h Deserializer M/S = $0 - READ$ Register 0x06 b[6:4] = 0x00'h	4.7			μs
f _{HIGH}	SCL High Period	Serializer M/S = $0 - R/W$ Register 0x05 = 0x40'h Deserializer M/S = $0 - READ$ Register 0x06 b[6:4] = 0x00'h	4.0			μs
t _{HD:STA}	Hold time for a start or a repeated start condition	Serializer M/S = 0 Register 0x05 = 0x40'h	4.0			μs
t _{SU:STA}	Set Up time for a start or a repeated start condition	Serializer M/S = 0 Register 0x05 = 0x40'h	4.7			μs
t _{HD:DAT}	Data Hold Time		0		3.45	μs
t _{SU:DAT}	Data Set Up Time		250			ns
t _{SU:STO}	Set Up Time for STOP Condition	Serializer M/S = 0	4.0			μs
t _f	SCL & SDA Fall Time				300	ns
t _{BUF}	Bus free time between a stop and start condition	Serializer M/S = 0	4.7			μs
t	NACK Time out	Serializer M/S = 1 Deserializer MODE = 1		1		ms
t _{TIMEOUT}		Register 0x06 b[2:0]=111'b		25		1113

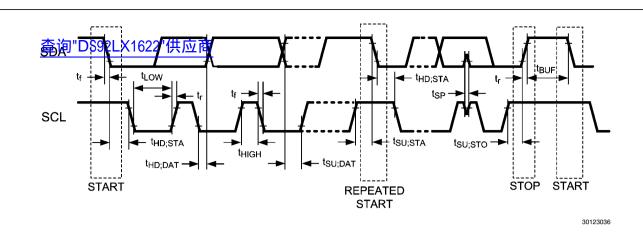


FIGURE 4. Bi-Directional Control Bus Timing

Bi-Directional Control Bus DC Characteristics (SCL, SDA) - I²C Compliant

Symbol	Parameter	Conditions	Min	Тур	Max	Units		
V _{IH}	Input High Level	SDA and SCL	0.7 x V _{DDIO}		V _{DDIO}	v		
V _{IL}	Input Low Level Voltage	SDA and SCL	GND		0.3 x V _{DDIO}	V		
V _{HY}	Input Hysteresis			>50		mV		
I _{oz}	TRI-STATE® Output Current	$PDB = 0V \ V_OUT = 0V \ or \ V_DD$	-20	±1	+20	μA		
I _{IN}	Input Current	SDA or SCL, Vin = V_{DDIO} or GND	-20	±1	+20	μA		
C _{IN}	Input Pin Capacitance			<5		pF		
V _{OL}	Low Level Output Voltage	SCL and SDA VDDIO = 3.0V IOL = 1.5 mA			0.36	v		
		SCL and SDA VDDIO = 1.71V IOL = 1 mA			0.36	V		

Note 1: "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions indicate conditions at which the device is functional; the device should not be operated beyond such conditions.

Note 2: The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

Note 3: Current into device pins is defined as positive. Current out of a device pin is defined as negative. Voltages are referenced to ground except VOD, ΔVOD, VTH and VTL which are differential voltages.

Note 4: Typical values represent most likely parametric norms at 1.8V or 3.3V, T_A = +25°C, and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.

Note 5: t_{PLD} and t_{DDLT} is the time required by the serializer and deserializer to obtain data lock when exiting power-down state with an active PCLK.

Note 6: t_{DCJ} is the maximum amount of jitter measured over 30,000 samples based on Time Interval Error (TIE).

Note 7: t_{DPJ} is the maximum amount the period is allowed to deviate measured over 30,000 samples.

Note 8: t_{DCCJ} is the maximum amount of jitter between adjacent clock cycles measured over 30,000 samples.

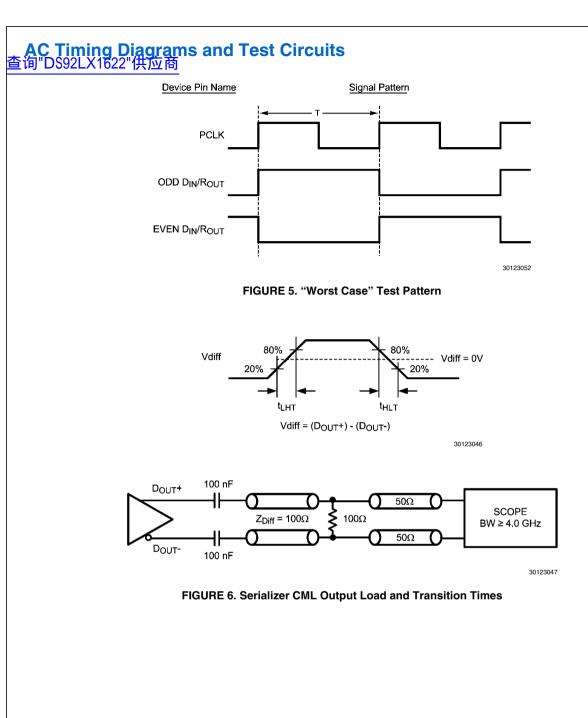
Note 9: Specification is guaranteed by design and is not tested in production.

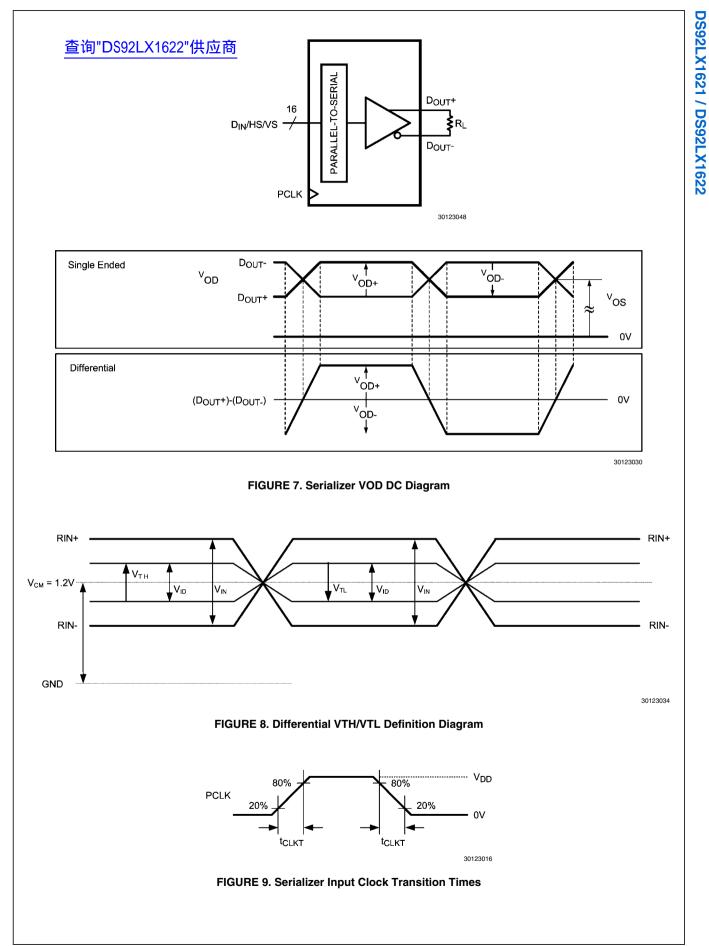
Note 10: Specification is guaranteed by characterization and is not tested in production.

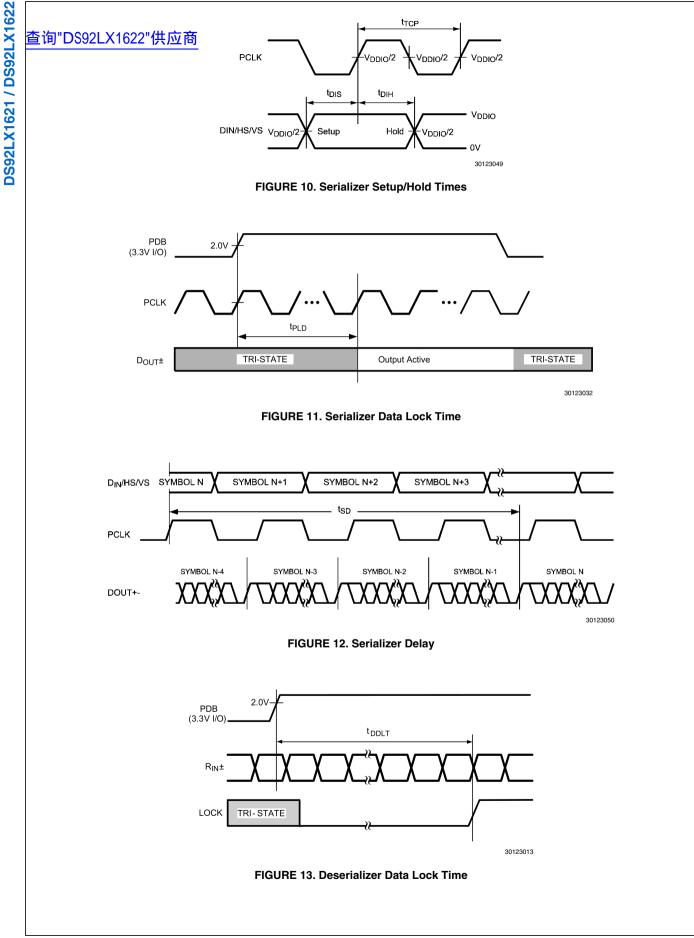
Note 11: t_{RJIT} max (0.61 UI) is limited by instrumentation and actual t_{RJIT} of in-band jitter at low frequency (<2MHz) is greater than 1 UI.

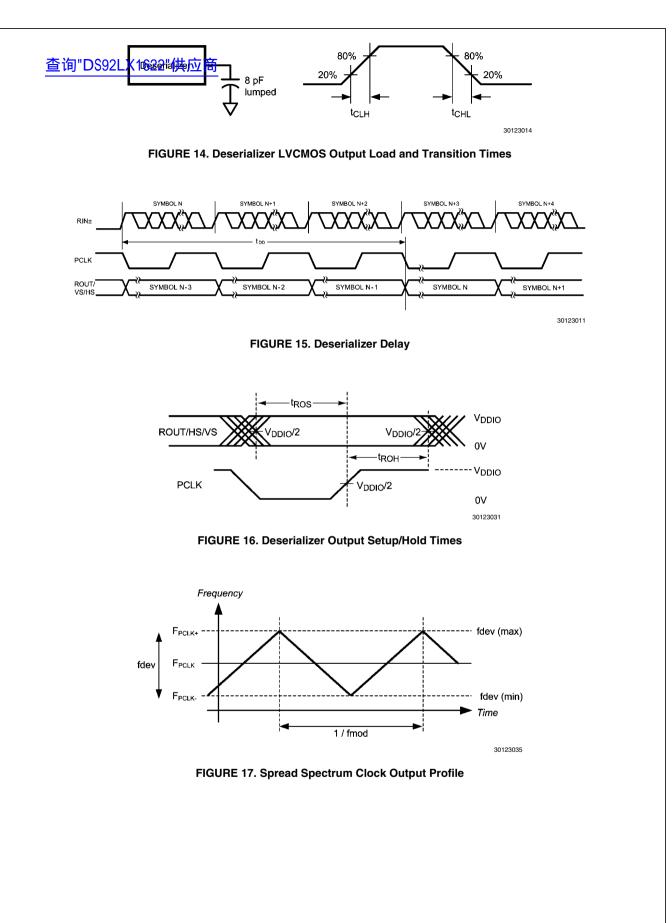
Note 12: UI – Unit Interval is equivalent to one ideal serialized data bit width. The UI scales with PCLK frequency.

Note 13: Recommended Input Timing Requirements are input specifications and not tested in production.









查询"DS92LX1622"供应商

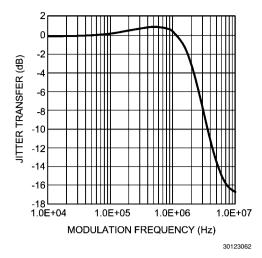


FIGURE 18. Typical Serializer Jitter Transfer Function at 43 MHz

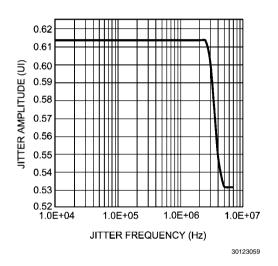


FIGURE 19. Typical Deserializer Input Jitter Tolerance Curve at 43 MHz

Addr (Hex)	Name	Bits	Field	R/W	Default	Description
0	I ² C Device ID	7:1	DEVICE ID	RW	0x58	7-bit address of Serializer; 0x58h (1011_000X) default
0	I ² C Device ID	0	SER ID	RW	0	0: Device ID is from CAD 1: Register I ² C Device ID overrides CAD
		7:3	RESERVED		0	Reserved
1	Reset	2	STANDBY	RW	0	Standby mode control. Retains control register data. Supported only when M/S = 0 0: Enabled. Low-current Standby mode with wake-up capability. Suspends all clocks and functions. 1: Disabled. Standby and wake-up disabled
		1	DIGITAL RESET0	RW	0 self clear	1: Resets the device to default register values. Does no affect device I ² C Bus or Device ID
		0	DIGITAL RESET1	RW	0 self clear	1: Digital Reset, retains all register values
2	Reserved	7:0	RESERVED		0x20'h	Reserved
	CRC Fault Tolerant Transmission	7	RX CRC CHECKER ENABLE	RW	1	Back Channel CRC Enable 0: Disable 1: Enable For propper CRC operation, control register 0x03h b[6 of the Deserializer must be enabled.
	CRC Fault Tolerant Transmission	6	TX CRC GEN ENABLE	RW	1	Forward Channel CRC Enable 0: Disable 1: Enable For propper CRC operation, control register 0x03h b[7 of the Deserializer must be enabled.
	VDDIO Control	5	VDDIO CONTOL	RW	1	Auto V _{DDIO} detect 0: Disable 1: Enable (auto detect mode)
3	VDDIO Mode	4		RW	1	VDDIO voltage set Only used when VDDIOCONTROL = 0 0: 1.8V 1: 3.3V
	I ² C Pass- Through	3	I ² C PASS- THROUGH	RW	1	I ² C Pass-Through Mode 0: Disabled 1: Enabled
	Reserved	2	RESERVED		0	Reserved
	PCLK_AUTO	1	PCLK_AUTO	RW	1	Switch over to internal 25 MHz oscillator clock in the absence of PCLK 0: Disable 1: Enable
	TRFB	0	TRFB	RW	1	Pixel Clock Edge Select: 0: Parallel Interface Data is strobed on the Falling Cloc Edge. 1: Parallel Interface Data is strobed on the Rising Cloc Edge.
		7:6	RESERVED		0	Reserved
4	CRC Transmission	5	CRC RESET	RW	0	1: CRC Reset. Clears CRC Error counter.
		4:0	RESERVED		1	Reserved

Addr	92LX1622"供J	、Bits 业 囵	Field	R/W	Default	Description
5	I ² C Bus Rate	7:0	I ² C BUS RATE	RW	0x40	I ² C ratio is determined by the following: $f_{SCL} = 6.25$ MHz / register value (in decimal) 0x40'h = ~100 kHz SCL (default) Note: Register values <0x32'h are NOT supported.
6	DES ID	7:1	DES DEV ID	RW	0x60	Deserializer Device ID = 0x60 (1100_000X) default
-		0	RESERVED		0	Reserved.
7	Slave ID	7:1	SLAVE DEV ID	RW	0	Slave Device ID. Must be programmed to communicat with remote slave device
		0	RESERVED		0	Reserved.
8	Reserved	7:0	RESERVED	RW	0	Reserved
9	Reserved	7:0	RESERVED	RW	1	Reserved
А	CRC Errors	7:0	CRC ERROR B0	R	0	Number of CRC errors - 8 LSBs
В	CRC Errors	7:0	CRC ERROR B1	R	0	Number of CRC errors - 8 MSBs
	Reserved	7:3	RESERVED		0	Reserved
	PCLK Detect	2	PCLK DETECT	R	0	1: Valid PCLK detected 0: Valid PCLK not detected
С	CRC Check	1	DES ERROR	R	0	1: CRC error during communication with Deserializer
	Cable Link	_				1: Cable link detected
	Detect Status	0	LINK DETECT	R	0	0: Cable link not detected
		7:4	RESERVED		1	Reserved
		3:2	RESERVED		0	Reserved
D	GPIO[0] Config	1	GPIO0 DIR	RW	0	0: Output 1: Input
		0	GPIO0 EN	RW	1	0: TRI-STATE® 1: Enabled
		7:4	RESERVED		0	Reserved
		3:2	RESERVED		0	Reserved
Е	GPIO[1] Config	1	GPIO1 DIR	RW	0	0: Output 1: Input
		0	GPIO1 EN	RW	1	0: TRI-STATE® 1: Enabled
		7:4	RESERVED		0	Reserved
		3:2	RESERVED		0	Reserved
F	GPIO[2] Config	1	GPIO2 DIR	RW	1	0: Output 1: Input
		0	GPIO2 EN	RW	1	0: TRI-STATE® 1: Enabled
		7:4	RESERVED		0	Reserved
		3:2	RESERVED		0	Reserved
10	GPIO[3] Config	1	GPIO3 DIR	RW	1	0: Output 1: Input
		0	GPIO3 EN	RW	1	0: TRI-STATE® 1: Enabled
		7:4	RESERVED		0	Reserved
		3:2	RESERVED		0	Reserved
11	GPIO[4] Config	1	GPIO4 DIR	RW	1	0: Output 1: Input
		0	GPIO4 EN	RW	1	0: TRI-STATE® 1: Enabled

Addr (Hex)	查询 ^{Name} 32LX	622	Field. 长应商	R/W	Default	Description
		7:4	RESERVED		0	Reserved
		3:2	RESERVED		0	Reserved
12	GPIO[5] Config	1	GPIO5 DIR	RW	1	0: Output 1: Input
		0	GPIO5 EN	RW	1	0: TRI-STATE® 1: Enabled
13	General Purpose Control Reg	7:0	GPCR[7] GPCR[6] GPCR[5] GPCR[4] GPCR[3] GPCR[2] GPCR[1] GPCR[0]	RW	0	0: LOW 1: HIGH

622	
LX1	
DS92	
21/1	
-X16	
S92L	

Addr (Hex)	Name	Bits	Field	R/W	Default	Description
0	l₂C Device ID	7:1	DEVICE ID	RW	0x60h	7-bit address of Deserializer; 0x60h (1100_000X) default
-		0	DES ID	RW	0	0: Device ID is from CAD 1: Register I ₂ C Device ID overrides CAD
		7:3	RESERVED			Reserved
1	1 Reset	2	REM_WAKEUP	RW	0	Remote Wake-up Select 1: Enable. Generate remote wakeup signal automatical wake-up the Serializer in Standby mode 0: Disable. Puts the Serializer (M/S = 0) in Standby mod when Deserializer M/S = 1
		1	DIGITALRESET0	RW	0 self clear	1: Resets the device to default register values. Does no affect device I2C Bus or Device ID
		0	DIGITALRESET1	RW	0 self clear	1: Digital Reset, retains all register values
	Reserved	7:6				Reserved
	Auto Clock	5	AUTO_CLOCK	RW	0	1: Output PCLK or Internal 25 MHz Oscillator clock 0: Only PCLK when valid PCLK present
	OSS Select	4	OSS_SEL	RW	0	Output Sleep State Select 0: Outputs = LOW , when LOCK = L 1: Outputs = TRI-STATE®, when LOCK = L
2	SSCG	3:0	SSCG		0	SSCG Select 0000: Normal Operation, SSCG OFF 0001: fmod (KHz) PCLK/2168, fdev ±0.50% 0010: fmod (KHz) PCLK/2168, fdev ±1.00% 0011: fmod (KHz) PCLK/2168, fdev ±1.50% 0100: fmod (KHz) PCLK/2168, fdev ±2.00% 0101: fmod (KHz) PCLK/1300, fdev ±0.50% 0110: fmod (KHz) PCLK/1300, fdev ±1.00% 0111: fmod (KHz) PCLK/1300, fdev ±1.50% 1000: fmod (KHz) PCLK/1300, fdev ±2.00% 1010: fmod (KHz) PCLK/868, fdev ±0.50% 1010: fmod (KHz) PCLK/868, fdev ±1.00% 1011: fmod (KHz) PCLK/868, fdev ±1.50% 1100: fmod (KHz) PCLK/868, fdev ±1.50% 1100: fmod (KHz) PCLK/868, fdev ±0.50% 1101: fmod (KHz) PCLK/650, fdev ±0.50% 1101: fmod (KHz) PCLK/650, fdev ±0.50% 1110: fmod (KHz) PCLK/650, fdev ±1.00% 1111: fmod (KHz) PCLK/650, fdev ±1.00%

Addr		Bite		R/W	Default	Description
(Hex)	查询 ^{Name} 92LX	622"(共应商間		Delault	Description
	CRC Fault Tolerant	7	Tx CRC CHECK ENABLE	RW	1	Back Channel CRC Enable 0: Disable 1: Enable For proper CRC operation, on Serailizer 0x03h b[6] control register must be Enabled.
	Transmission	6	Rx CRC GEN ENABLE	RW	1	Foward Channel CRC Enable 0: Disable 1: Enable For proper CRC operation, on Serailizer 0x03h b[7] control register must be Enabled.
	VDDIO Control	5	VDDIO CONTROL	RW	1	Auto voltage control 0: Disable 1: Enable (auto detect mode)
3	VDDIO Mode	4	VDDIO MODE	RW	0	VDDIO voltage set Only used when VDDIOCONTROL = 0 0: 1.8V 1: 3.3V
	I ² C Pass-Through	3	I ² C PASS- THROUGH	RW	1	I ² C Pass-Through Mode 0: Disabled 1: Enabled
	Auto ACK	2	AUTO ACK	RW	0	0: Disable 1: Enable
	CRC Reset	1	CRC RESET	RW	0	1: CRC reset
	RRFB	0	RRFB	RW	1	Pixel Clock Edge Select 0: Parallel Interface Data is strobed on the Falling Clock Edge 1: Parallel Interface Data is strobed on the Rising Clock Edge.
4	EQ Feature Control1	7:0	EQ	RW	0	00 [°] h: ~0.0 dB 01 [°] h: ~4.5 dB 03 [°] h: ~6.5 dB 07 [°] h: ~7.5 dB 0F [°] h: ~8.0 dB 1F [°] h: ~11.0 dB 3F [°] h: ~12.5 dB FF [°] h: ~14.0 dB
5	Reserved	7:0	RESERVED		0	Reserved

Addr	Name	Bits	Field	B/W	Default	Description
	<u>\$92LX1622"供</u>					P
	Reserved SCL Prescale	6:4	RESERVED		0	Prescales the SCL clock line when reading data byte from a slave device (M/S = 0) 000 : ~100 kHz SCL (default) 001 : ~125 kHz SCL 101 : ~11 kHz SCL 110 : ~33 kHz SCL 111 : ~50 kHz SCL 0therwise are NOT suggested
6	Remote NACK	3	REM_NACK_TIM ER	RW	1	Other values are NOT supported. Remote NACK Timer Enable In slave mode (MODE = 1) if bit is set the I2C core will automatically timeout when no acknowledge condition was detected. 1: Enable 0: Disable
	Remote NACK	2:0	NACK_TIMEOUT	RW	0	Remote NACK Timeout. 000: 2.0 ms 001: 5.2 ms 010: 8.6 ms 011: 11.8 ms 100: 14.4 ms 101: 18.4 ms 110: 21.6 ms 111: 25.0 ms
7	SER ID	7:1	SER DEV ID	RW	0x58h	Serializer Device ID = 0x58 (1011_000X) default
		0	RESERVED		0	Reserved
8	ID[0] Index	7:1	ID[0] INDEX	RW	0	Target slave Device ID slv_id1 [7:1]
		0	RESERVED		0	Reserved.
9	ID[1] Index	7:1	ID[1] INDEX	RW	0	Target slave Device ID slv_id1 [7:1]
		0	RESERVED		0	Reserved.
А	ID[2] Index	7:1	ID[2] INDEX	RW	0	Target slave Device ID slv_id2 [7:1]
		0	RESERVED		0	Reserved.
В	ID[3] Index	7:1 0	ID[3] INDEX RESERVED	RW	0	Target slave Device ID slv_id3 [7:1] Reserved.
		7:1	ID[4] INDEX	RW	0	Target slave Device ID slv_id4 [7:1]
С	ID[4] Index	0	RESERVED		0	Reserved.
		7:1	ID[5] INDEX	RW	0	Target slave Device ID slv_id5 [7:1]
D	ID[5] Index	0	RESERVED	1100	0	Reserved.
		7:1	ID[6] INDEX	RW	0	Target slave Device ID slv_id6 [7:1]
Е	ID[6] Index	0	RESERVED	1100	0	Reserved.
		7:1	ID[7] INDEX	RW	0	Target slave Device ID slv_id7 [7:1]
F	ID[7] Index	0	RESERVED		0	Reserved.
		7:1	ID[0] MATCH	RW	0	Alias to match Device ID slv_id0 [7:1]
10	ID[0] Match	0	RESERVED		0	Reserved.
		7:1	ID[1] MATCH	RW	0	Alias to match Device ID slv_id1 [7:1]
11	ID[1] Match	0	RESERVED		0	Reserved.
		7:1	ID[2] MATCH	RW	0	Alias to match Device ID slv_id2 [7:1]
12	ID[2] Match	0	RESERVED		0	Reserved.
		7:1	ID[3] MATCH	RW	0	Alias to match Device ID slv_id3 [7:1]
13	ID[3] Match	0	RESERVED	-	0	Reserved.
		7:1	ID[4] MATCH	RW	0	Alias to match Device ID slv_id4 [7:1]
14	ID[4] Match		RESERVED		0	Reserved.

Addr (Hex)	查询 ^{Narre} 92LX1	Bits 622 (共应商 ^{Field}	R/W	Default	Description
15 ID[5] Match		7:1	ID[5] MATCH	RW	0	Alias to match Device ID slv_id5 [7:1]
15		0	RESERVED		0	Reserved
16 ID[6] Match	7:1	ID[6] MATCH	RW	0	Alias to match Device ID slv_id6 [7:1]	
16 ID[6] Match		0	RESERVED		0	Reserved.
17	17 ID[7] Match		ID[7] MATCH	RW	0	Alias to match Device ID slv_id7 [7:1]
17		0	RESERVED		0	Reserved.
18	Reserved	7:0	RESERVED		0	Reserved
19	Reserved	7:0	RESERVED		1	Reserved
1A	CRC Errors	7:0	CRC ERROR B0	R	0	Number of CRC errors 8 LSBs
1B	CRC Errors	7:0	CRC ERROR B1	R	0	Number of CRC errors 8 MSBs
	Reserved	7:3	RESERVED		0x02'h	Reserved
	CRC Check	2	SER ERROR	R	0	CRC error during communication with Serializer on Forward Channel
1C	Signal Detect Status	1		R	0	0: Active signal not detected
		-			0	1: Active signal detected
	LOCK Pin Status			R	0	0: CDR/PLL Unlocked
		_				1: CDR/PLL Locked
		7:3	RESERVED	RW	0	Reserved.
		2	GPIO0 SET	SPIO0 SET RW 1	1: Configured as GPIO	
40						0: Configured as ROUT data (OSS_SEL controlled)
1D	GPIO[0] Config	1	GPIO0 DIR RW	1	0: Output	
					N 1	1: Input 0: TRI-STATE®
		0	GPIO0 EN	RW		1: Enabled
		7:3	RESERVED	RW	0	Reserved.
		7.0				1: Configured as GPIO
	GPIO[1] Config	2	GPIO1 SET	RW	1	0: Configured as ROUT data (OSS_SEL controlled)
1E				RW 1		0: Output
		1	GPIO1 DIR		1	1: Input
					1	0: TRI-STATE®
		0	GPIO1 EN	RW		1: Enabled
	GPIO[2] Config	7:3	RESERVED	RW	0	Reserved
		2	GPIO2 SET	RW	0	1: Configured as GPIO 0: Configured as ROUT0 data (OSS_SEL controlled)
1F						0: Output
		1	GPIO2 DIR	RW	0	1: Input
						0: TRI-STATE®
		0	GPIO2 EN	RW	1	1: Enabled
	GPIO[3] Config	7:3	RESERVED	RW	0	Reserved
						1: Configured as GPIO
		2	GPIO3 SET	RM	RW 0	0: Configured as ROUT1 data (OSS_SEL controlled)
20		4				0: Output
		1	GPIO3 DIR	RW	0	1: Input
		0	GPIO3 EN	RW	1	0: Tri-state
				¥¥ ت	'	1: Enabled

Addr 查(询 划)	S92LX10222"供/	,Bits 业冏	Field	R/W	Default	Description
		7:3	RESERVED	RW	0	Reserved
		2	GPIO4 SET	RW	0	1: Configured as GPIO 0: Configured as ROUT2 data (OSS_SEL controlled)
21	GPIO[4] Config	1	GPIO4 DIR	RW	0	0: Output 1: Input
		0	GPIO4 EN	RW	1	0: TRI-STATE® 1: Enabled
22	GPIO[5] Config	7:3	RESERVED	RW	0	Reserved
		2	GPIO5 SET	RW	0	1: Configured as GPIO 0: Configured as ROUT3 data (OSS_SEL controlled)
		1	GPIO5 DIR	RW	0	0: Output 1: Input
		0	GPIO5 EN	RW	1	0: TRI-STATE® 1: Enabled
23	General Purpose Control Reg	7:00	GPCR[7] GPCR[6] GPCR[5] GPCR[4] GPCR[3] GPCR[2] GPCR[1] GPCR[0]	RW	0	0: LOW 1: HIGH
24	BIST	0	BIST_EN	RW	0	BIST Enable 0: Normal operation 1: Bist Enable
25	BIST_ERR	7:00	BIST ERR	R	0	Bist Error Counter

Functional Description 面面的的名称。 The DS971X1621745921X1622 Channel Link III chipset is

The DS92LX16217DS92LX1622 Channel Link III chipset is intended for camera applications. The Serializer/ Deserializer chipset operates from a 10 MHz to 50 MHz pixel clock frequency. The DS92LX1621 transforms a 16-bit wide parallel LVCMOS data bus along with a bi-directional control bus into a single high-speed differential pair. The high speed serial bit stream contains an embedded clock and DC-balance information which enhances signal quality to support AC coupling. The DS92LX1622 receives the single serial data stream and converts it back into a 16-bit wide parallel data bus together with the bi-directional control bus.

The bi-directional channel function of the DS92LX1621 / DS92LX1622 provides bi-directional communication between

the image sensor and the host device (FPGA, frame grabber, display, etc.). The integrated back channel transfers data bidirectionally over the same differential pair used for video data interface. This interface offers advantages over other chipsets by eliminating the need for additional wires for programming and control. The bi-directional control channel is controlled via an I²C port. The bi-directional control channel offers asynchronous communication and is not dependent on video blanking intervals.

SERIAL FRAME FORMAT

The DS92LX1621 / DS92LX1622 chipset will transmit and receive a pixel of data in the following format:

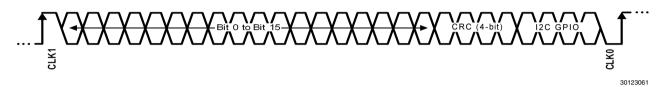


FIGURE 20. Serial Bitstream for 28-bit Symbol

The High Speed Forward Channel (HS_FC) is a 28-bit symbol composed of 16 bits of data containing camera data & control information transmitted from Serializer to Deserializer. CLK1 and CLK0 represent the embedded clock in the serial stream. CLK1 is always HIGH and CLK0 is always LOW. This data payload is optimized for signal transmission over an AC coupled link. Data is randomized, balanced and scrambled. The data payload may be checked using a 4-bit CRC function. The CRC monitors the link integrity of the serialized data and reports when an error condition is detected.

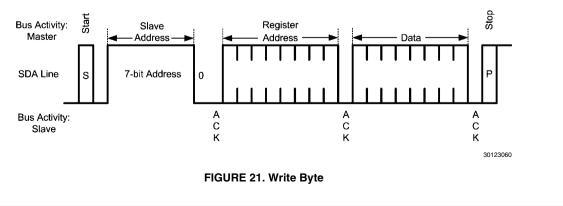
The bi-directional control data is transferred over the single serial link along with the high-speed forward data. This architecture provides a full duplex low speed forward and backward path across the serial link together with a high speed forward channel without the dependence of the video blanking phase.

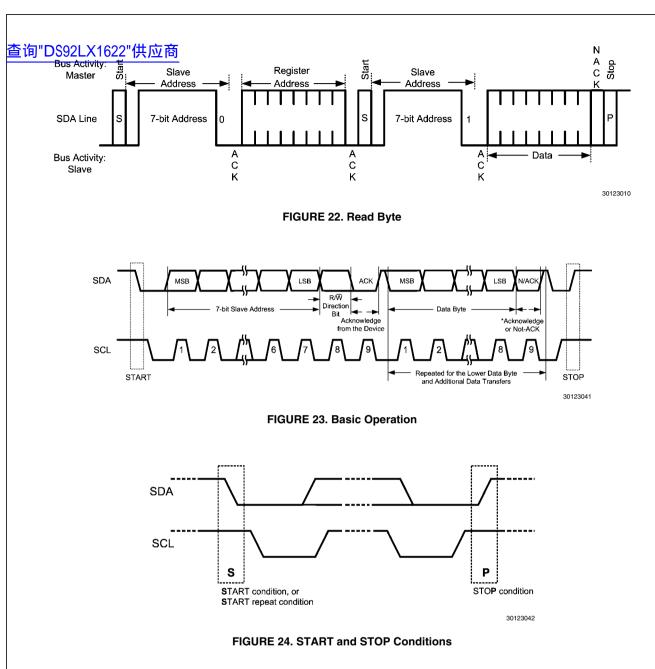
DESCRIPTION OF BI-DIRECTIONAL CONTROL BUS AND I²C MODES

The I²C compatible interface allows programming of the DS92LX1621, DS92LX1622, or an external remote device (such as a camera) through the bi-directional control channel. Register programming transactions to/from the DS92LX1621 / DS92LX1622 chipset are employed through the clock (SCL) and data (SDA) lines. These two signals have open drain I/Os and both lines must be pulled-up to VDDIO by external resistor. *Figure 4* shows the timing relationships

of the clock (SCL) and data (SDA) signals. Pull-up resistors or current sources are required on the SCL and SDA busses to pull them high when they are not being driven low. A logic zero is transmitted by driving the output low. A logic high is transmitted by releasing the output and allowing it to be pulled-up externally. The appropriate pull-up resistor values will depend upon the total bus capacitance and operating speed. The DS92LX1621 / DS92LX1622 I²C bus data rate supports up to 100 kbps according to I²C specification.

To start any data transfer, the DS92LX1621 / DS92LX1622 must be configured in the proper I²C mode. Each device can function as an I²C slave proxy or master proxy depending on the mode determined by M/S pin. The Ser/Des interface acts as a virtual bridge between Master controller (MCU) and the remote device. When the M/S pin is set to HIGH, the device is treated as a slave proxy; acts as a slave on behalf of the remote slave. When addressing a remote peripheral or Serializer/ Deserializer (not wired directly to the MCU), the slave proxy will forward any byte transactions sent by the Master controller to the target device. When M/S pin is set to LOW, the device will function as a master proxy device; acts as a master on behalf of the I²C master controller. Note that the devices must have complementary settings for the M/S configuration. For example, if the Serializer M/S pin is set to HIGH then the Deserializer M/S pin must be set to LOW and viceversa.





SLAVE CLOCK STRETCHING

In order to communicate and synchronize with remote devices on the I²C bus through the bi-directional control channel, slave clock stretching must be supported by the I²C master controller/MCU. The chipset utilizes bus clock stretching (holding the SCL line low) during data transmission; where the I²C slave pulls the SCL line low prior to the 9th clock of every I²C data transfer (before the ACK signal). The slave device will not control the clock and only stretches it until the remote peripheral has responded; which is typically in the order of 12 μ s (typical).

CAD PIN ADDRESS DECODER

The CAD pin is used to decode and set the physical slave address of the Serializer/Deserializer (I²C only) to allow up to six devices on the bus using only a single pin. The pin sets one of six possible addresses for each Serializer/Deserializer device. The pin must be pulled to VDD (1.8V, NOT VDDIO)) with a 10 k Ω resistor and a pull down resistor (RID) of the recommended value to set the physical device address. The recommended maximum resistor tolerance is 0.1% worst case (0.2% total tolerance).

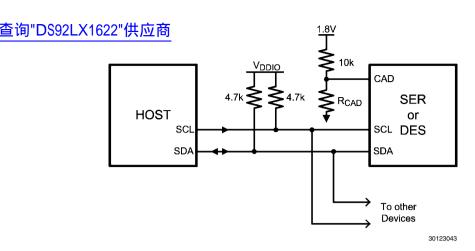


FIGURE 25. Serial Control Bus Connection

CAD Resistor Value - DS92LX1621 Ser					
Resistor RID Ω (±0.1%)	Address 7'b	Address 8'b 0 appended (WRITE)			
0 GND	7b' 101 1000 (h'58)	8b' 1011 0000 (h'B0)			
2.0k	7b' 101 1001 (h'59)	8b' 1011 0010 (h'B2)			
4.7k	7b' 101 1010 (h'5A)	8b' 1011 0100 (h'B4)			
8.2k	7b' 101 1011 (h'5B)	8b' 1011 0110 (h'B6)			
12.1k	7b' 101 1100 (h'5C)	8b' 1011 1000 (h'B8)			
39.0k	7b' 101 1110 (h'5E)	8b' 1011 1100 (h'BC)			

	CAD Resistor Value - DS92LX1622 Des				
Resistor RID Ω (±0.1%)	Address 7'b	Address 8'b 0 appended (WRITE)			
0 GND	7b' 110 0000 (h'60)	8b' 1100 0000 (h'C0)			
2.0k	7b' 110 0001 (h'61)	8b' 1100 0010 (h'C2)			
4.7k	7b' 110 0010 (h'62)	8b' 1100 0100 (h'C4)			
8.2k	7b' 110 0011 (h'62)	8b' 1101 0110 (h'C6)			
12.1k	7b' 110 0100 (h'62)	8b' 1101 1000 (h'C8)			
39.0	7b' 110 0110 (h'66)	8b' 1100 1100 (h'CC)			

CAMERA MODE OPERATION

In Camera mode, I²C transactions originate from the Master controller at the Deserializer side. The I²C slave core in the Deserializer will detect if a transaction is intended for the Serializer or a slave at the Serializer. Commands are sent over the bi-directional control channel to initiate the transactions. The Serializer will receive the command and generate an I²C transaction on its local I²C bus. At the same time, the Serializer will capture the response on the I²C bus and return the response on the forward channel link. The Deserializer parses the response and passes the appropriate response to the Deserializer I²C bus.

To configure the devices for camera mode operation, set the Serializer M/S pin to LOW and the Deserializer M/S pin to HIGH. Before initiating any I²C commands, the Deserializer needs to be programmed with the target slave device addresses and Serializer device address. SER_DEV_ID Regis-

ter 0x07h sets the Serializer device address and SLAVE_x_MATCH/SLAVE_x_INDEX registers 0x08h~0x17h set the remote target slave addresses. In slave mode the address register is compared with the address byte sent by the I²C master. If the addresses are equal to any of registers values, the I²C slave will acknowledge and hold the bus to propagate the transaction to the target device otherwise it returns no acknowledge.

DISPLAY MODE OPERATION

In Display mode, I²C transactions originate from the controller attached to the Serializer. The I2C slave core in the Serializer will detect if a transaction targets (local) registers within the Serialier or the (remote) registers within the Deserializer or a remote slave connected to the I²C master interface of the Deserializer. Commands are sent over the forward channel link to initiate the transactions. The Deserializer will receive the command and generate an I²C transaction on its local I2C bus. At the same time, the Deserializer will capture the respons on the bi-directional control channel. The Serializer parses the response and passes the appropriate response to the Serializer I²C bus.

The physical device ID of the I²C slave in the Serializer is determined by the analog voltage on the ID[x] input. It can be reprogrammed by using the DEVICE_ID register and setting the bit . The device ID of the logical I2C slave in the Deserializer is determined by programming the DES ID in the Serializer. The state of the CAD] input on the Deserializer is used to set the device ID. The I²C transactions between Ser/Des will be bridged between the host controller to the remote slave.

To configure the devices for display mode operation, set the Serializer M/S pin to HIGH and the Deserializer M/S pin to LOW. Before initiating any I²C commands, the Serializer needs to be programmed with the target slave device address and Serializer device address. DES_DEV_ID Register 0x06h sets the Deserializer device address and SLAVE_DEV_ID register 0x7h sets the remote target slave address. If the I²C slave address matches any of registers values, the I²C slave will hold the transaction allowing read or write to target device. Note: In Display mode operation, registers 0x08h~0x17h on Deserializer must be reset to 0x00.

CRC (CYCLIC REDUNDANCY CHECK)

A 4-bit CRC per symbol is reserved for checking the link integrity during transmission. The reporting status pin (PASS) is provided on the Deserializer side, which flags any mismatch of data transmitted to and from the remote device. The Deserializer's PLL must first be locked (LOCK pin is HIGH) to ensure the PASS status is valid. This error detection handling generates an interrupt signal onto the PASS output pin; notifying the host controller as soon as any errors are identified. When an error occurs, the PASS will asserts LOW. An adjustable interrupt threshold register is also available for managing the data flow.

ERROR DETECTION

The DS92LX1621 / DS92LX1622 chipset provides several error detection operations for ensuring data integrity in long distance transmission and reception. The data error detection function offers user flexibility and usability of performing bitby-bit and data transmission error checking. The error detection operating modes support data validation of the following signals:

 Bi-directional Control Channel control data detection across serial link

- Control VSYNC and HSYNC signals across serial link
- Parallel video/pixel data across serial link

PROGRAMMABLE CONTROLLER

An integrated I²C slave controller is embedded in each of the DS92LX1621 Serializer and DS92LX1622 Deserializer. It must be used to access and program the extra features embedded within the configuration registers. Refer to *Table 1* and *Table 2* for details of control registers.

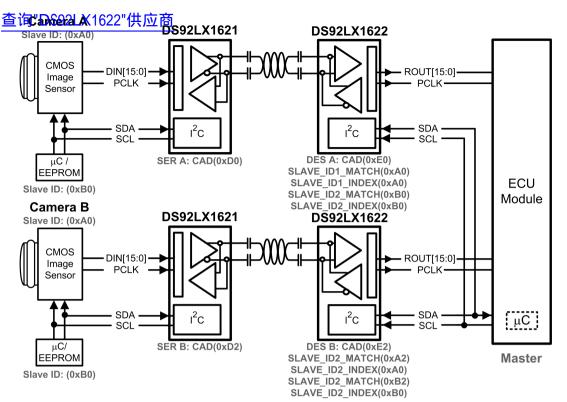
MULTIPLE DEVICE ADDRESSING

Some applications require multiple camera devices with the same fixed address to be accessed on the same I²C bus. The DS92LX1621 / DS92LX1622 provide slave ID matching/aliasing to generate different target slave addresses when connecting more than two identical devices together on the same bus. This allows the slave devices to be independently addressed. Each device connected to the bus is addressable through a unique ID by programming of the SLAVE_ID_MATCH register on Deserializer. This will remap the SLAVE_ID_MATCH address to the target SLAVE_ID_IN-DEX address; up to 8 ID indexes are supported. The host controller must keep track of the list of I²C peripherals in order to properly address the target device. In a camera application, the microcontroller is located on the Deserializer side. In this case, the microcontroller programs the slave address matching registers and handles all data transfers to and from all slave I²C devices. This is useful in the event where camera modules are removed or replaced. For example in the configuration shown in Figure 26:

- Host device (FPGA, frame grabber, etc.) is the I²C master and has an I²C master interface
- The I²C protocol is bridged from DES A to SER A and from DES B to SER B
- The I²C interfaces in SER A and SER B are both master interfaces

If the master controller transmits I²C slave 0xA0, the DES A address 0xE0 will forward the transaction to remote Camera A. If the controller transmits slave address 0xA2, the DES B 0xE2 will recognize that 0xA2 is mapped to 0xA0 and will be transmitted to the remote Camera B. If controller sends command to address 0xB2, the DES B 0xE2 will forward transaction to slave device 0xB0.

The Slave ID index/match is supported only in the camera mode (SER: M/S pin = L; DES: M/S pin = H). For Multiple device addressing in display mode (SER: M/S pin = H; DES: M/S pin = L), use the I²C pass through function.



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FIGURE 26. Multiple Device Addressing

I²C PASS THROUGH

the second secon

communication to only specific devices on the remote bus. The feature is effective for both Camera mode and Display mode.

For example in the configuration shown in Figure 27:

If master controller transmits I²C transaction for address 0xA0, the SER A with I²C pass through enabled will transfer I²C commands to remote Camera A. The SER B with I²C pass through disabled, any I²C commands will be bypassed on the I²C bus to Camera B.

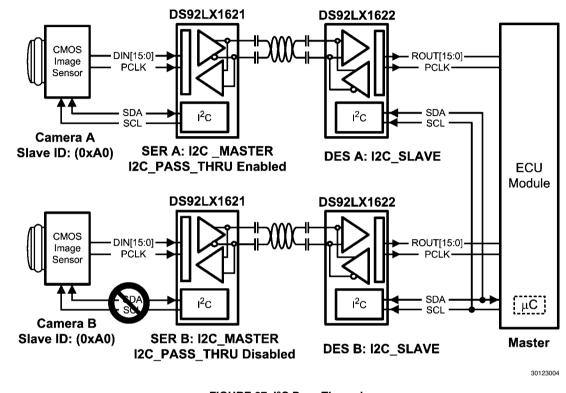


FIGURE 27. I²C Pass Through

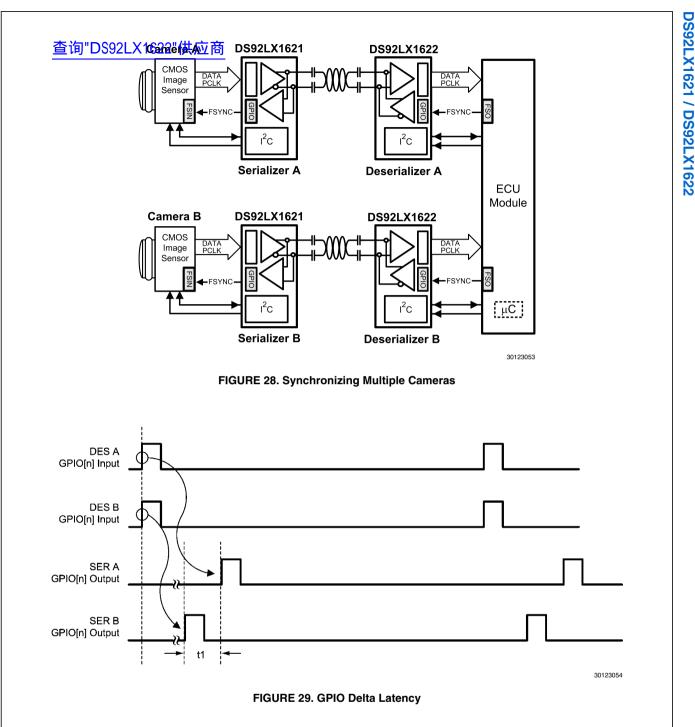
SYNCHRONIZING MULTIPLE CAMERAS

For applications requiring multiple cameras for frame-synchronization, it is recommended to utilize the General Purpose Input/Output (GPIO) pins to transmit control signals to synchronize multiple cameras together. To synchronize the cameras properly, the system controller needs to provide a field sync output (such as a vertical or frame sync signal) and the cameras must be set to accept an auxiliary sync input. The vertical synchronize signal corresponds to the start and end of a frame and the start and end of a field. Note this form of synchronization timing relationship has a non-deterministic latency. After the control data is reconstructed from the bidirectional control channel, there will be a time variation of the GPIO signals arriving at the different target devices (between the parallel links). The maximum latency delta (t1) of the GPIO data transmitted across multiple links is $25 \ \mu$ s.

Note: The user must verify that the timing variations between the different links are within their system and timing specifications.

For example in the configuration shown in Figure 28:

The maximum time (t1) between the rising edge of GPIO (i.e. sync signal) arriving at Camera A and Camera B is 25 µs.



GENERAL PURPOSE I/O (GPIO)

The DS92LX1621 / DS92LX1622 has up to 6 GPIO (2 dedicated and 4 programmable). GPIO[0] and GPIO[1] are always available and GPIO[2:5] are available depending on the parallel data bus size. DIN/ROUT[0:3] can be programmed into GPIOs (GPIO[2:5]) when the parallel data bus is less than 12 bits wide (10-bit data + HS,VS). Each GPIO can be configured as either an input or output port. The GPIO maximum switching rate is up to 66 kHz when configured for communication between Deserializer GPI to Serializer GPO. Whereas data flow configured for communication between Serializer GPI to Deserializer GPO is limited by the maximum data rate of the PCLK.

AT-SPEED BIST (BISTEN, PASS)

An optional AT SPEED Built in Self Test (BIST) feature supports at speed testing of the high-speed serial and the bidirectional control channel link. Control pins at the Deserializer are used to enable the BIST test mode and allow the system to initiate the test and set the duration. A HIGH on PASS pin indicates that all payloads received during the test were error free during the BIST duration test. A LOW on this pin at the conclusion of the test indicates that one or more payloads were detected with errors.

The BIST duration is defined by the width of BISTEN. BIST starts when Deserializer LOCK goes HIGH and BISTEN is set HIGH. BIST ends when BISTEN goes LOW. Any errors detected after the BIST Duration are not included in PASS logic.

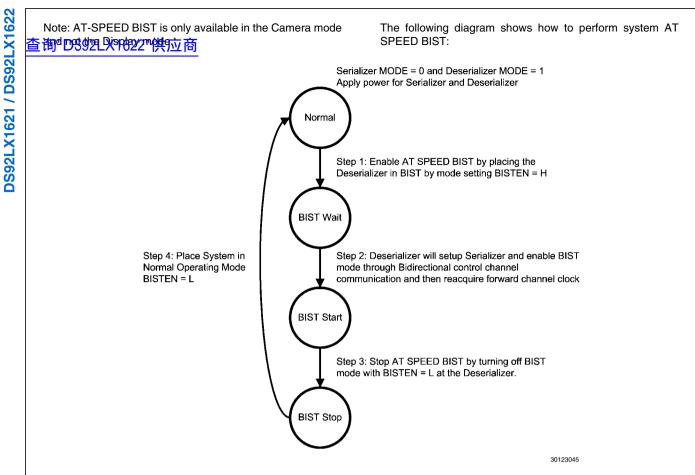


FIGURE 30. AT-SPEED BIST System Flow Diagram

Step 1: Place the Deserializer in BIST Mode.

Serializer and Deserializer power supply must be supplied. Enable the AT SPEED BIST mode on the Deserializer by set-

ting the BISTEN pin High. The DS92LX1622 GPIO[1:0] pins are used to select the PCLK frequency of the on-chip oscillator for the BIST test on high speed data path.

TABLE 3. BIST Oscillator Frequency Select

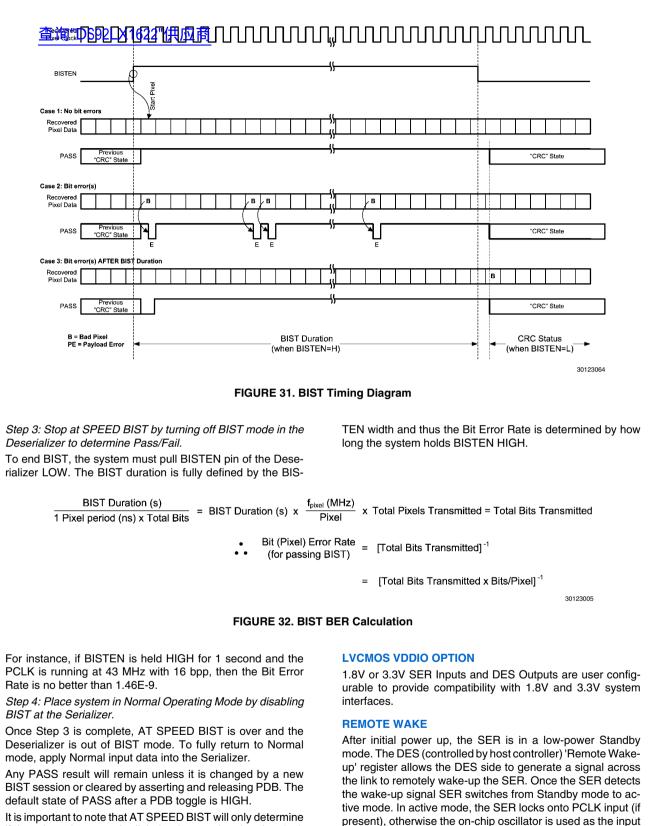
DES GPIO [1:0]	Oscillator Source	min (MHz)	typ (MHz)	max (MHz)
00	External PCLK	10		50
01	Internal		50	
10	Internal		25	
11	Internal		12.5	

The Deserializer GPIO[1:0] set to 00 will bypass the on-chip oscillator and an external oscillator to Serializer PCLK input is required. This allows the user to operate BIST under different frequencies other than the predefined ranges.

Step 2: Enable AT SPEED BIST by placing the Serializer into BIST mode.

The deserializer will communicate through the back-channel to configure Serializer into BIST mode. Once the BIST mode is set, the Serializer will initiate BIST transmission to the Deserializer.

Wait 10 ms for Deserializer to acquire lock and then monitor the LOCK pin transition from LOW to HIGH. At this point, AT SPEED BIST is operational and the BIST process has begun. The Serializer will start transfer of an internally generated PRBS data pattern through the high speed serial link. This pattern traverses across the interconnecting link to the Deserializer. Check the status of the PASS pin; a HIGH indicates a pass, a LOW indicates a fail. A fail will stay LOW for ½ a clock cycle. If two or more bits fail in a row the PASS pin will toggle ½ clock cycle HIGH and ½ clock cycle low. The user can use the PASS pin to count the number of fails on the high speed link. In addition, there is a defined SER and DES register that will keep track of the accumulated error count. The Serializer DS92LX1621 GPIO[0] pin will be assigned as a PASS flag error indicator for the bi-directional control channel link.



if there is an issue on the link that is not related to the clock and data recovery of the link (whose status is flagged with LOCK pin).

clock source. Note the host controller should monitor the LOCK pin and confirm LOCK = H before performing any I²C communication across the link.

For Remote Wake-up to function properly:

The chipset needs to be configured in Camera mode: Serializer M/S = 0 and Deserializer M/S = 1

Serializer is in remote wake-up mode by default at power
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The serializer can also be put into standby mode by programming the Deserializer remote wakeup control register 0x01 b [2] REM_WAKEUP to 0.

POWERDOWN

The SER has a PDB input pin to ENABLE or Powerdown the device. The modes can be controlled by the host and is used to disable the link to save power when the remote device is not operational. An auto mode is also available. In this mode, the PDB pin is tied HIGH and the SER switches over to an internal oscillator when the PCLK stops or not present. When a PCLK starts again, the SER will then lock to the valid input PCLK and transmits the data to the DES. In powerdown mode, the high-speed driver outputs are static (HIGH).

The DES has a PDB input pin to ENABLE or Powerdown the device. This pin can be controlled by the system and is used to disable the DES to save power. An auto mode is also available. In this mode, the PDB pin is tied HIGH and the DES will enter powerdown when the serial stream stops. When the serial stream starts up again, the DES will lock to the input stream and assert the LOCK pin and output valid data. In powerdown mode, the Data and PCLK outputs are set by the OSS_SEL control register.

POWER UP REQUIREMENTS AND PDB PIN

It is required to delay and release the PDB input signal after VDD (VDDn and VDDIO) power supplies have settled to the recommended operating voltages. A external RC network can be connected to the PDB pin to ensure PDB arrives after all the VDD have stabilized.

SIGNAL QUALITY ENHANCERS

Des - Receiver Input Equalization (EQ)

The receiver inputs provided input equalization filter in order to compensate for loss from the media. The level of equalization is controlled via register setting.

EMI REDUCTION

Des - Receiver Staggered Output

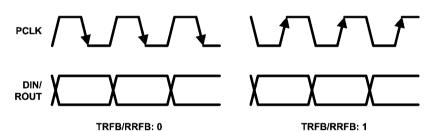
The Receiver staggered outputs allows for outputs to switch in a random distribution of transitions within a defined window. Outputs transitions are distributed randomly. This minimizes the number of outputs switching simultaneously and helps to reduce supply noise. In addition it spreads the noise spectrum out reducing overall EMI.

Des Spread Spectrum Clocking Compatibility

The DS92LX1622 parallel data and clock outputs have programmable SSCG ranges from 9 kHz–66 kHz and $\pm 0.5\%$ – $\pm 2\%$ from 20 MHz to 50 MHz. The modulation rate and modulation frequency variation of output spread is controlled through the SSC control registers.

PIXEL CLOCK EDGE SELECT (TRFB/RRFB)

The TRFB/RRFB selects which edge of the Pixel Clock is used. For the SER, this register determines the edge that the data is latched on. If TRFB register is 1, data is latched on the Rising edge of the PCLK. If TRFB register is 0, data is latched on the Falling edge of the PCLK. For the DES, this register determines the edge that the data is strobed on. If RRFB register is 1, data is strobed on the Rising edge of the PCLK. If RRFB register is 0, data is strobed on the Falling edge of the PCLK.



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FIGURE 33. Programmable PCLK Strobe Select

Applications Information 查询"DS92LX1622"供应商

the device in an AC-coupled application, insert external AC coupling capacitors in series in the Channel Link III signal path as illustrated in *Figure 34*.

AC COUPLING

The SER/DES supports only AC-coupled interconnects through an integrated DC balanced decoding scheme. To use

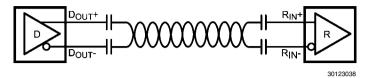


FIGURE 34. AC-Coupled Application

For high-speed Channel Link III transmissions, the smallest available package should be used for the AC coupling capacitor. This will help minimize degradation of signal quality due to package parasitics. The most common used capacitor value for the interface is $0.1\mu F$.

TYPICAL APPLICATION CONNECTION

Figure 35 shows a typical connection of the DS92LX1621 Serializer.



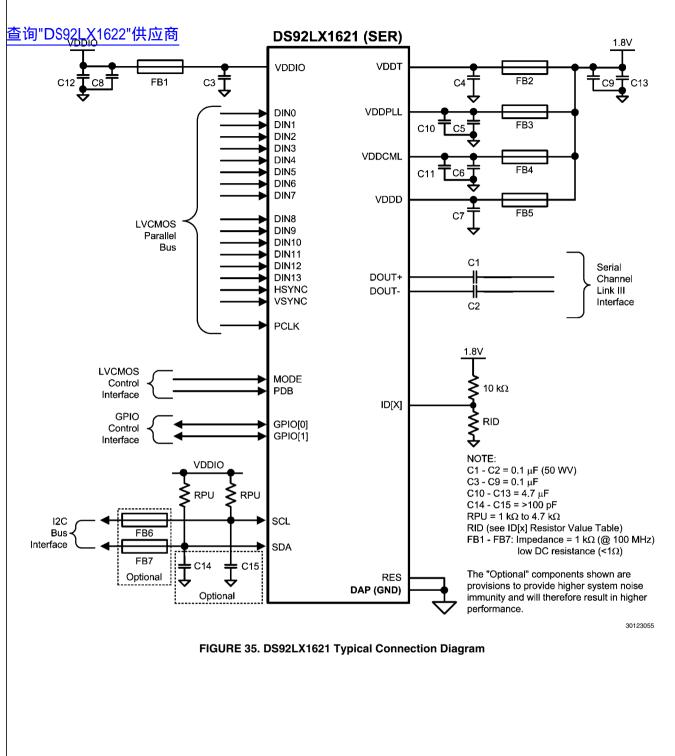


Figure 36 shows a typical connection of the DS92LX1622 Deseri查询"DS92LX1622"供应商

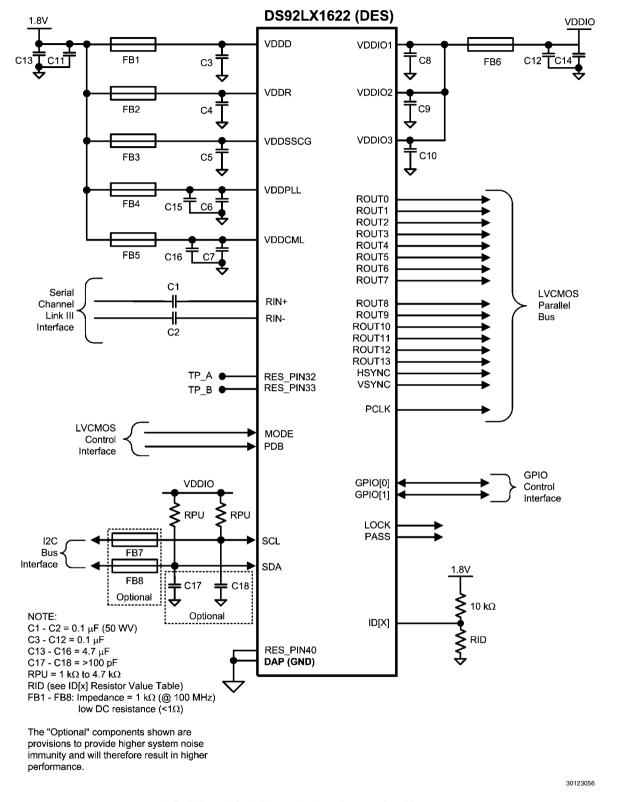


FIGURE 36. DS92LX1622 Typical Connection Diagram

TRANSMISSION MEDIA

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Other cable parameters that may limit the cable's performance boundaries are: cable attenuation, near-end crosstalk and intra-pair skew.

For obtaining optimal performance, the following is recommended:

- Use Shielded Twisted Pair (STP) cable
- 100Ω differential impedance and 24 AWG (or lower AWG) cable
- · Low intra-pair skew, impedance matched
- Terminate unused conductors

PCB LAYOUT AND POWER SYSTEM CONSIDERATIONS

Circuit board layout and stack-up for the Ser/Des devices should be designed to provide low-noise power feed to the device. Good layout practice will also separate high frequency or high-level inputs and outputs to minimize unwanted strav noise pickup, feedback and interference. Power system performance may be greatly improved by using thin dielectrics (2 to 4 mils) for power / ground sandwiches. This arrangement provides plane capacitance for the PCB power system with low-inductance parasitics, which has proven especially effective at high frequencies, and makes the value and placement of external bypass capacitors less critical. External bypass capacitors should include both RF ceramic and tantalum electrolytic types. RF capacitors may use values in the range of 0.01 uF to 0.1 uF. Tantalum capacitors may be in the 2.2 uF to 10 uF range. Voltage rating of the tantalum capacitors should be at least 5X the power supply voltage being used.

Surface mount capacitors are recommended due to their smaller parasitics. When using multiple capacitors per supply pin, locate the smaller value closer to the pin. A large bulk capacitor is recommend at the point of power entry. This is typically in the 50uF to 100uF range and will smooth low frequency switching noise. It is recommended to connect power and ground pins directly to the power and ground planes with

bypass capacitors connected to the plane with via on both ends of the capacitor. Connecting power or ground pins to an external bypass capacitor will increase the inductance of the path.

A small body size X7R chip capacitor, such as 0603, is recommended for external bypass. Its small body size reduces the parasitic inductance of the capacitor. The user must pay attention to the resonance frequency of these external bypass capacitors, usually in the range of 20-30 MHz. To provide effective bypassing, multiple capacitors are often used to achieve low impedance between the supply rails over the frequency of interest. At high frequency, it is also a common practice to use two vias from power and ground pins to the planes, reducing the impedance at high frequency.

Some devices provide separate power for different portions of the circuit. This is done to isolate switching noise effects between different sections of the circuit. Separate planes on the PCB are typically not required. Pin Description tables typically provide guidance on which circuit blocks are connected to which power pin pairs. In some cases, an external filter many be used to provide clean power to sensitive circuits such as PLLs.

Use at least a four layer board with a power and ground plane. Locate LVCMOS signals away from the differential lines to prevent coupling from the LVCMOS lines to the differential lines. Closely-coupled differential lines of 100 Ohms are typically recommended for differential interconnect. The closely coupled lines help to ensure that coupled noise will appear as common-mode and thus is rejected by the receivers. The tightly coupled lines will also radiate less.

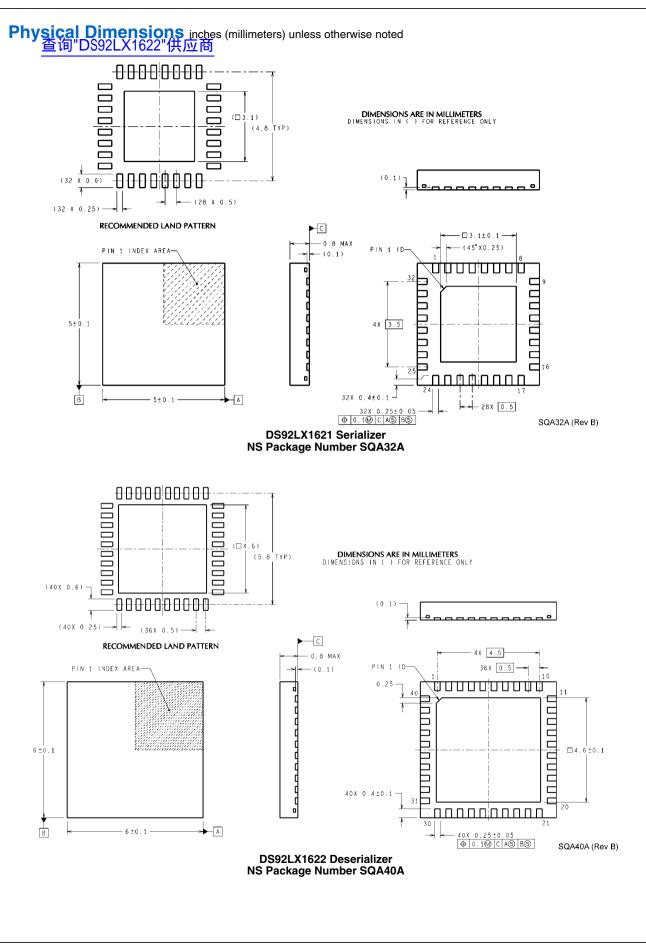
Information on the LLP style package is provided in National Application Note: AN-1187.

INTERCONNECT GUIDELINES

See AN-1108 and AN-905 for full details.

- Use 100Ω coupled differential pairs
 - Use the S/2S/3S rule in spacings
 - S = space between the pair
 - ____ 2S = space between pairs
 - 3S = space to LVCMOS signal
- Minimize the number of Vias
- Use differential connectors when operating above 500Mbps line speed
- Maintain balance of the traces
- · Minimize skew within the pair

Additional general guidance can be found in the LVDS Owner's Manual - available in PDF format from the National web site at: www.national.com/lvds



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Notes

For more National Semiconductor product information and proven design tools, visit the following Web sites at: www.national.com

Pr	oducts	Design Support		
Amplifiers	www.national.com/amplifiers	WEBENCH® Tools	www.national.com/webench	
Audio	www.national.com/audio	App Notes	www.national.com/appnotes	
Clock and Timing	www.national.com/timing	Reference Designs	www.national.com/refdesigns	
Data Converters	www.national.com/adc	Samples	www.national.com/samples	
Interface	www.national.com/interface	Eval Boards	www.national.com/evalboards	
LVDS	www.national.com/lvds	Packaging	www.national.com/packaging	
Power Management	www.national.com/power	Green Compliance	www.national.com/quality/green	
Switching Regulators	www.national.com/switchers	Distributors	www.national.com/contacts	
LDOs	www.national.com/ldo	Quality and Reliability	www.national.com/quality	
LED Lighting	www.national.com/led	Feedback/Support	www.national.com/feedback	
Voltage References	www.national.com/vref	Design Made Easy	www.national.com/easy	
PowerWise® Solutions	www.national.com/powerwise	Applications & Markets	www.national.com/solutions	
Serial Digital Interface (SDI)	www.national.com/sdi	Mil/Aero	www.national.com/milaero	
Temperature Sensors	www.national.com/tempsensors	SolarMagic™	www.national.com/solarmagic	
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